



Product Change Notification / KSRA-24DTJN091

Date:

07-Nov-2020

Product Category:

Jitter Attenuators, Voice Audio

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3996, 3996.001 and 3996.002 Final Notice: Qualification of MMT as a new assembly site for selected MSCC MT898xxx, MT90xxxx, MT912xxx and ZL800xxx device families available in 28L (11.5x11.5x4.4mm), 44L PLCC (16.6x16.6x4.4mm) and 68L PLCC (24.2x24.2x4.4 mm) packages using palladium coated copper with gold flash (CuPdAu) bond wire

Affected CPNs:

[KSRA-24DTJN091_Affected_CPN_11072020.pdf](#)

[KSRA-24DTJN091_Affected_CPN_11072020.csv](#)

Notification Text:

PCN Status:

Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of MMT as a new assembly site for selected MSCC MT898xxx, MT90xxxx, MT912xxx and ZL800xxx device families available in 28L (11.5x11.5x4.4mm), 44L PLCC (16.6x16.6x4.4mm) and 68L PLCC (24.2x24.2x4.4 mm) packages using palladium coated copper with gold flash (CuPdAu) bond wire

Pre Change:

Assembled at ASEM assembly site using copper (Cu) bond wire, YIZ8143 die attach and CEL 9240HF10AK-G1 molding

compound material

Post Change:

Assembled at MMT assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, 3280 die attach and G600V molding compound material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	ASE Group -Malaysia / ASEM	Microchip Technology Thailand (Branch) / MMT
Wire material	Cu wire	CuPdAu Wire
Die attach material	YIZ8143	3280
Molding compound material	CEL 9240HF10AK-G1	G600V
Lead frame material	A194	A194

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve manufacturability and on-time delivery by qualifying MMT as new assembly site

Change Implementation Status:In Progress

Estimated First Ship Date:December 07, 2020 (date code: 2049)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	November 2019					-->	November 2020				December 2020			
	44	45	46	47	48		45	46	47	48	49	50	51	52
Initial PCN Issue Date		X												
Qual Report Availability							X							
Final PCN Issue Date							X							
Estimated Implementation Date										X				

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:November 07, 2019: Issued initial notification.

November 07, 2020: Issued final notification. Attached the Qualification Report. Revised the affected parts list, notification subject and description of change to update the device family affected. Provided estimated first ship date to be on December 07, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products

Attachments:

[PCN_KSRA-24DTJN091_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

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Affected Catalog Part Numbers (CPN)

MT9041BP1
ZL80001QAA1
ZL80002QAA1
MT9042CP1
MT9041BPR1
ZL80001QAB1
ZL80002QAB1
MT9123AP1
MT9123APR1
MT9122AP1
MT90812AP1
MT8985AP1
MT9074AP1
MT9074APR1